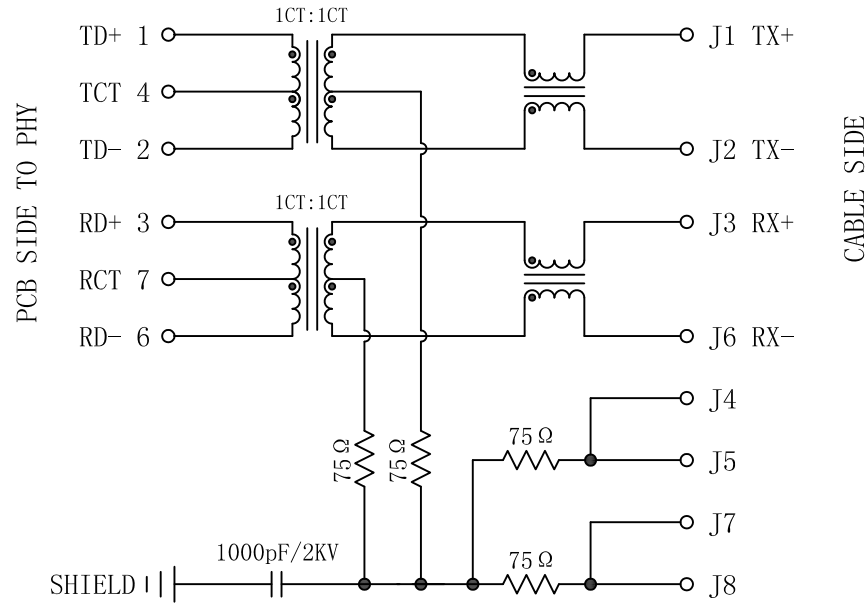


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2012-05-07	



ELECTRICAL SPECIFICATIONS @25°C

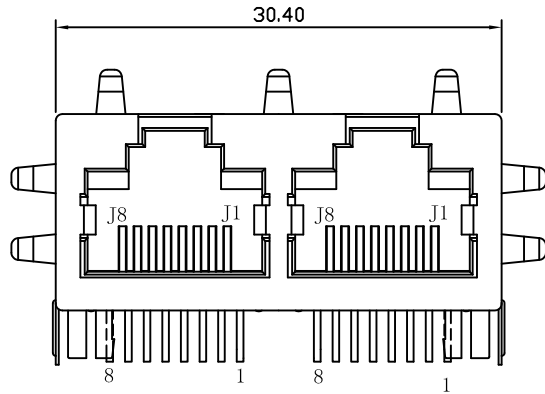
- Turn Ratio ($\pm 3\%$):
TX=1CT:1CT RX=1CT:1CT
- Inductance OCL:
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- DCR:
1.2 Ω MAX
- Insertion Loss:
-1.1dB MAX @1~100MHz
- Return Loss:
-18dB MIN @1~30MHz
-16dB MIN @30~60MHz
-12dB MIN @60~100MHz
- Cross talk:
-30dB MIN @1~100MHz
- Common Mode Rejection:
-30dB MIN @1~100MHz
- Hipot Test: 1500Vrms
- Operating Temperature Range: 0°C~70°C.



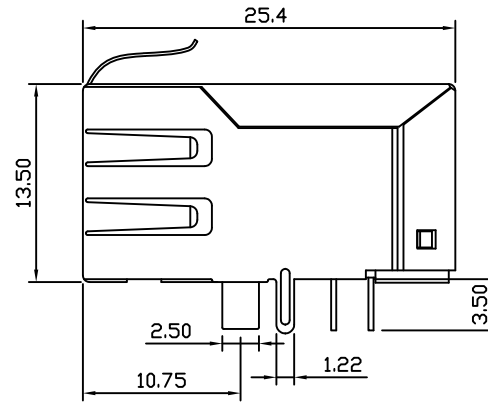
X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.25	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: 1*2 RJ45 Connector with 10/100 Base-T Integrated Magnetics
ANGLES ±1°	UNIT: mm	PART NO.: LPJ21028CNL
	SCALE: 2/1	SHEET: 1/2
	REV: A	DWG NO.: LP12050716

Mechanical:

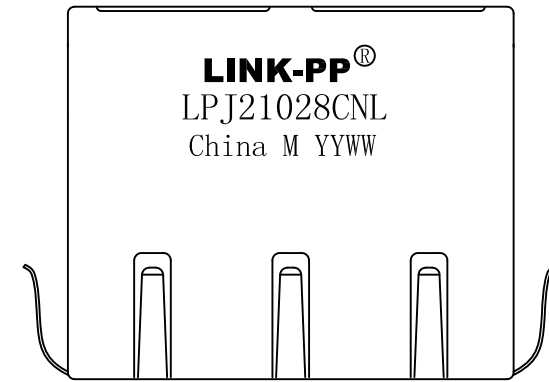
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2012-05-07	



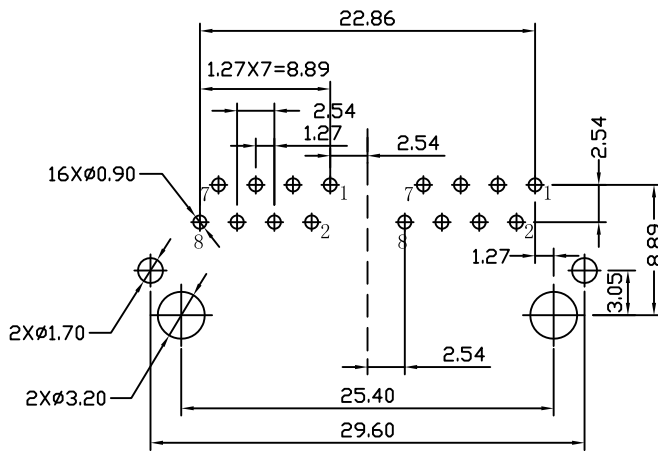
Front Side View



Left Side View



Top Side View



Suggested PCB Layout (Top View)



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing: Thermoplastic PBT+30%G.F UL94V-0
 Contact: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: SUS 201-1/2H Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 250°C, 5 Sec.
5. UL Certification: File Number E484635.

X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.25	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: 1*2 RJ45 Connector with 10/100 Base-T Integrated Magnetics
ANGLES ±1°	UNIT: mm	PART NO.: LPJ21028CNL
	SCALE: 2/1	SHEET: 2/2
	REV: A	DWG NO.: LP12050716